

Title (en)  
WAFER GRIPPING FINGERS

Title (de)  
FINGER ZUM GREIFEN VON WAFERN

Title (fr)  
DOIGTS DE PRISE DE TRANCHES

Publication  
**EP 1105257 A1 20010613 (EN)**

Application  
**EP 00916400 A 20000316**

Priority  
• US 0006895 W 20000316  
• US 12464799 P 19990316

Abstract (en)  
[origin: WO0054941A1] Wafers (12) are gripped by edge holders (14, 16, 18) which have curved, and optionally, Teflon coated grooves (34) with a radius of curvature greater than that of the edge of the wafer being held. This minimizes stress and torque applied to the wafer that might distort its shape and impair the measurement accuracy of wafer parameters.

IPC 1-7  
**B25J 15/10**

IPC 8 full level  
**B25J 15/08** (2006.01); **B25J 15/10** (2006.01); **H01L 21/66** (2006.01); **H01L 21/677** (2006.01); **H01L 21/687** (2006.01)

CPC (source: EP)  
**B25J 15/103** (2013.01); **H01L 21/68707** (2013.01)

Citation (search report)  
See references of WO 0054941A1

Designated contracting state (EPC)  
DE GB

DOCDB simple family (publication)  
**WO 0054941 A1 20000921**; **WO 0054941 A9 20011129**; EP 1105257 A1 20010613; JP 2002539621 A 20021119

DOCDB simple family (application)  
**US 0006895 W 20000316**; EP 00916400 A 20000316; JP 2000605000 A 20000316